Thapar Institute of Engg. & Tech [Deemed University], Patiala

End semester Exam, Dec 2006

Subject Instructor: Urmi Agnihotri Microelectronics & I.C.s [EC-029] Max. Time: 3 hours

Max. Marks: 45

Note: 1.] Attempt any 9 questions. Each question carries 5marks.Don't over attempt.

2.] Use diffusivity of boron as 4*10⁻³cm²/sec.

- 3.] See your answer sheets on 13th at 5.10pm in my room.
- Q1. i.] Explain with help of diagram and chemical equations, Czochralski crystal growing technique.
 - ii.] List the various steps in the final manufacture of a wafer from the raw silicon.
- Q2. i.] Write a short note on dry, HCl Dry, Wet, High-pressure and plasma oxidation.
 - ii.] Discuss any two oxide properties.
- Q3. i.1 Discuss plasma surface interactions.
 - ii.] What are plasma etchers and barrel reactors?
 - iii] Discuss side wall mechanism
- Q4. Write detailed note on the usage of silicon on insulators.
- O5. Write short notes on:
 - ii. Electron beam lithography iii. Optical lithography i.] Ion beam lithography
- Q6. i.] What is range theory? Explain in detail.
 - ii.] Draw only the complete schematic of typical ion-implantation machine.
- Q7. Explain in detail the causes imperfect yield.
- ii.] Thermal design considerations Q8. Explain i.] Package types

iii.] Mechanical design considerations iv.] Electrical design considerations

- Q9. Find the diffusivity from a known impurity profile. Assume that boron is diffused into n type Si crystal substrate with doping concentration of 1015 atoms/cm3, and also that the diffusion profile can be described by gaussian function. Using a diffusion time of 60 min, one obtains measured junction depth of 2 microns and a surface concentration of 1018 cm-3.
- Q10. Equilibrium concentrations of boron at solid and liquid interface are 10-3 and 10-4 atoms/cm3 respectively. If the boundary layer thickness is 0.0025mm, find the value of equilibrium segregation coefficient and effective segregation coefficient for a pull rate of 2.7mm/min.
- Q11.i.] Find the linear rate constant if the parabolic rate constant for wet oxidation is 0.287µm/h and the value of A is 0.226µm.
 - ii.] Calculate the mean free path (in cm) of the dopant if the pressure in the MBE chamber is 10-8 Torr.
- Q12, i.] What is rents rule? Estimate the number of gates that can be included on a logic array chip, which is to be assembled in a 100 I/O package. Assume alpha =2.5 and beta =0.45.
 - ii.] Draw the sequence only for packaging starting from wafer preparation till test showing material and piece part.